RF 104

In Reply Please Quote Our Reference

Your Ref : 9869SG2106/KJR/ACK/NFZ
Our Ref : 2013053582/130725/TMMSBS/8478
Date : 25/07/2013
Writer's Direct Line :

VENUGOPAL MADHAV ANNAMDAS
SCHOOL OF MECHANICAL AND AEROSPACE ENGINEERING, NANYANG TECHNOLOGICAL UNIVERSITY, BLOCK N3, 50 NANYANG AVENUE, SINGAPORE 639798
SINGAPORE

Dear Sir,

Singapore Patent Application No.: 201305358-2
Title of invention: ELECTROMECHANICAL CHARGE DENSITY (EMCD) AND WAVE FORM PROPAGATION (WFP) METHODS FOR DIAGNOSTICS OF ENGINEERING MATERIALS, COMPONENTS AND STRUCTURES
Applicant(s): NANYANG TECHNOLOGICAL UNIVERSITY (SG)

NOTIFICATION – AN APPLICATION FOR A PATENT ON THE ABOVE-MENTIONED INVENTION HAS BEEN FILED IN SINGAPORE

This notification is to inform you that the above-identified application for a patent has been filed in Singapore in accordance with the Patents Act.

Enclosed herewith for your attention is a copy of the Patents Form 8, which was furnished by the Applicants in compliance with Rule 18(2) of the Patents Rules.

Yours faithfully

Muhammad Salihin Bin Sabah

for REGISTRAR OF PATENTS
SINGAPORE

Encl. – a copy of Patents Form 8
INTELLECTUAL PROPERTY OFFICE OF SINGAPORE

PF8

Common Form Index
Entry Date: 12-Jul-2013 14:14:27
Priority: Normal
Classification: Confidential
Lodgement Date: 12-Jul-2013
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ReceiptNo: 833909

General Indexes
Your Reference: 9869SG2106/KJR/AKC/NFZ
Application Number:
Title of Invention: ELECTROMECHANICAL CHARGE DENSITY (EMCD) AND WAVE FORM PROPAGATION (WFP) METHODS FOR DIAGNOSTICS OF ENGINEERING MATERIALS, COMPONENTS AND STRUCTURES

Name of Applicant
Name: NANYANG TECHNOLOGICAL UNIVERSITY

Number of Inventors
Number of Inventors: 2

Details of Inventor
Name: VENU GOPAL MADHAV ANNAMDAS
Address: SCHOOL OF MECHANICAL AND AEROSPACE ENGINEERING, NANYANG TECHNOLOGICAL UNIVERSITY, BLOCK N3, 50 NANYANG AVENUE, SINGAPORE 639798
Country of permanent residence: SG
Citizenship: IN
The above inventor was resident in Singapore at any time during the period of invention: Yes

Details of Inventor
Name: HOCK LYE JOHN PANG
Address: SCHOOL OF MECHANICAL AND AEROSPACE ENGINEERING, NANYANG TECHNOLOGICAL UNIVERSITY, BLOCK N3, 50 NANYANG AVENUE, SINGAPORE 639798
Country of permanent residence: SG
Citizenship: SG
The above inventor was resident in Singapore at any time during the period of invention: Yes

The Applicant(s) Derived the Right from the Inventor(s) to be Granted the Said Application
As Follows: Contract of employment
Others:

Details of Agent
Name:
Firm: SPRUSON & FERGUSON (ASIA) PTE LTD

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RF 101

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Our Ref : 2013053582/130725/TIMMSBS/8479
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Writer's Direct Line :

SPRUSON & FERGUSON (ASIA) PTE LTD
P.O. BOX 1531
ROBINSON ROAD POST OFFICE
SINGAPORE 903031

Dear Sir(s),

Singapore Patent Application No.: 201305358-2
Title of invention: ELECTROMECHANICAL CHARGE DENSITY (EMCD) AND WAVE FORM PROPAGATION (WFP) METHODS FOR DIAGNOSTICS OF ENGINEERING MATERIALS, COMPONENTS AND STRUCTURES
Applicant(s): NANYANG TECHNOLOGICAL UNIVERSITY (SG)

ALLOCATION OF DATE OF FILING

Thank you for the documents that you have submitted in relation to your application for the grant of a patent which was received on 12/07/2013.

2. We are pleased to inform you that the application has been accorded a Date of Filing 12/07/2013.

3. The application number allocated to the application includes, at its end, a check digit. The full application number, including the check digit, should be quoted in all correspondences concerning proceedings in respect of the application up to the grant of the patent. When the application is published under section [27] of the Patents Act (Cap. 221), it will be accorded a seven-digit serial number. This number should be used only when seeking to identify patents after grant and to make enquiries concerning entries in the register.

4. If you have any further queries, please do not hesitate to contact the undersigned.

Yours faithfully,

Muhammad Salihin Bin Sabah

for REGISTRAR OF PATENTS
INTELLECTUAL PROPERTY OFFICE OF SINGAPORE

Encl. Notes for Information including Patents Work Sharing Programmes
PAYMENT OF FILING FEES – RULE 19(2)

Where the filing fee is not paid within the same day of filing the application, the fee shall be paid within 1 month from that day. Failure to pay the filing fee within the 1 month period shall result in the application being treated as having been abandoned.

FILING OF PATENT CLAIMS – RULE 26(5)

Where claims have not been filed within the same day of filing the application, the application shall be treated as having been abandoned unless one or more claims are filed within:

(i) where there is no declared priority date, 12 months from the date of filing of the application;
(ii) where there is a declared priority date, 12 months from the declared priority date or 2 months from the date of filing of the application, whichever expires later; or
(iii) where a new application has been filed under section 20 (3), 26 (11) or 47 (4), 2 months from the date the new application was filed.

INVENTORSHIP – RULE 18

Where an applicant is not an inventor of the invention, a statement identifying the inventor(s) and indicating the derivation of the right of the applicant to be granted a patent on the invention must be filed on Patents Form 8 within 16 months from the declared priority date or where there is no declared priority date, the date of filing of the application.

PRIORITY CLAIMS – RULE 9B(1)

Where a declaration claiming priority has been made at the time of filing the application, the applicant shall furnish to the Registry within 16 months from the declared priority date the application or file number of each priority application specified in the declaration.

FILING A PATENT APPLICATION OUTSIDE SINGAPORE

- National Security Check – Section 34

If the Singapore application is the applicant’s first application for the invention, an application for the same invention is not to be filed outside Singapore without first getting written authority from the Registry, unless 2 months have lapsed since the filing of the Singapore application and no directions by the Registry have been given under Section 33.

- Claiming priority on your Singapore application

In general, if the applicant wishes to file a patent application outside Singapore claiming priority from the Singapore application, the overseas application would have to be filed within 12 months from the date of filing of the Singapore application.

GENERAL

For details on how to proceed with your application, references should be made to the provisions found in the Patents Act and Rules.

PATENTS WORK SHARING PROGRAMMES

The Intellectual Property Office of Singapore (IPOS) has established Patent Prosecution Highway (PPH) pilot programmes with the United States Patent and Trademark Office (USPTO), the Japan Patent Office (JPO) and the Korean Intellectual Property Office (KIPO). The PPH allows applicants who have first filed a patent application in Singapore and who are looking to file in the US and/or Japan and/or Korea, to take advantage of expedited examination in these countries using Singapore’s examination results. A similar advantage applies for applicants who have first filed patent applications in any of these countries to enjoy expedited registration in Singapore.

IPOS has also established similar co-operative work arrangements with the IP Offices of eight ASEAN countries, namely – Brunei Darussalam, Cambodia, Indonesia, Lao PDR, Malaysia, the Philippines, Thailand and Viet Nam. The ASEAN Patent Examination Co-operation (ASPEC) allows applicants who have filed corresponding patent applications in one or more participating ASEAN IP Office to submit the first available search and examination documents in any other participating ASEAN IP Office.

These work sharing programmes can bring about substantial time savings to the patent applicant and improve the quality of search and examination. To find out more about PPH and ASPEC, please refer to our website at www.ipos.gov.sg [About IP > What is Intellectual Property and what are the different types? > What is a patent? > Applying for a patent].

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Dear Sir,

Singapour Patent Application No.: 201305358-2
Title of Invention: ELECTROMECHANICAL CHARGE DENSITY (EMCD) AND WAVE FORM PROPAGATION (WFP) METHODS FOR DIAGNOSTICS OF ENGINEERING MATERIALS, COMPONENTS AND STRUCTURES
Applicant(s): NANYANG TECHNOLOGICAL UNIVERSITY (SG)

FILING OF PATENT CLAIM(S)

We refer to the above-mentioned patent application filed on 12/07/2013.

We note that no patent claim(s) has been filed by the applicant(s).

The applicants are invited to file patent claim(s) within (12) months from the date of filing if the said application contains no declared priority date. If there is a declared priority date, the due date would be (12) months from the declared priority date, or (2) months from the actual date of filing, whichever expires later [Rule 26(5)].

We wish to inform that formalities examination under Section 28 of the Patents Act would NOT be carried out until patent claim(s) has been filed by the applicants.

Under section 26(12) of the Patents Act, failure to do so within the prescribed period shall result in the application being treated as having been abandoned.

If you have any further queries, please do not hesitate to contact the undersigned.

Thank you.

Yours faithfully,

Muhammad Salihin Bin Sabah
for REGISTRAR OF PATENTS
SINGAPURE
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Our Ref : 2013053582/130725/TMCKO/8455
Date : 25/07/2013
Writer’s Direct Line : 63316543

SPRUSON & FERGUSON (ASIA) PTE LTD
P.O. BOX 1531
ROBINSON ROAD POST OFFICE
SINGAPORE 903031

Dear Sir,

Singapore Patent Application No.: 201305358-2
Title of invention: ELECTROMECHANICAL CHARGE DENSITY (EMCD) AND WAVE FORM PROPAGATION (WFP) METHODS FOR DIAGNOSTICS OF ENGINEERING MATERIALS, COMPONENTS AND STRUCTURES
Applicant(s): NANYANG TECHNOLOGICAL UNIVERSITY (SG)

SECURITY CLEARANCE UNDER SECTION 34 OF THE PATENTS ACT

We refer to your patent application that was filed with the Registry on 12/07/2013.

The person(s) [resident(s) in Singapore] mentioned in the said patent application may proceed (if desired) to file or cause to be filed patent application(s) in respect of the same invention outside Singapore, as from the date of this letter.

Thank you.

Yours faithfully,

CHEUNG KAR CONN (MS)
ASSISTANT REGISTRAR
for REGISTRAR OF PATENTS
SINGAPORE